



Material Content Data Sheet



Sales Product Name		IPD60R2K0C6		Issued		20. July 2018			
MA#		MA000973226							
Package		PG-TO252-3-341		Weight*		381.31 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.272	0.33	0.33	3335	3335	
leadframe	non noble metal	iron	7439-89-6	0.248	0.07		652		
	inorganic material	phosphorus	7723-14-0	0.075	0.02		195		
	non noble metal	copper	7440-50-8	248.124	65.07	65.16	650721	651568	
wire	non noble metal	aluminium	7429-90-5	4.429	1.16	1.16	11614	11614	
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.698	0.45		4453		
	plastics	brominated resin	-	1.819	0.48		4771		
	organic material	carbon black	1333-86-4	1.941	0.51		5089		
	plastics	epoxy resin	-	16.373	4.29		42940		
	inorganic material	silicondioxide	60676-86-0	99.453	26.08	31.81	260822	318075	
leadfinish	non noble metal	tin	7440-31-5	3.740	0.98	0.98	9809	9809	
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1334	1334	
solder	noble metal	silver	7440-22-4	0.041	0.01		107		
	non noble metal	tin	7440-31-5	0.033	0.01		85		
	non noble metal	lead	7439-92-1	1.553	0.41	0.43	4073	4265	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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